

Talks • Posters • Lunch • Awards • Vendor Show • Short Courses

## Tuesday, May 23<sup>th</sup>, 2023

# at the **Sheraton Airport Hotel in Albuquerque**

We are accepting abstracts for talks (15 min slot) and posters (with 2 min intro) related to

science at low pressures and/or controlled atmospheres including films and coatings,

microelectronics, nanostructures, surfaces and interfaces, plasmas, vacuum, and

manufacturing processes

## Submit Abstracts by April 24<sup>th</sup>, 2023:

#### www.nmavs.org

For abstract submission and registration

REGISTRATION: FREE LUNCH IS PROVIDED

PRIZES AWARDED FOR BEST PRESENTATION: POST-DOC; GRADUATE STUDENT; UNDERGRADUATE; PROFESSIONAL TECHNICIAN

#### **PRIZES WILL ALSO BE PRESENTED FOR BEST POSTER**

Best student talk will also receive up to \$2000 travel reimbursement for this year's AVS International Symposium in Portland Oregon Winners announced at the end of the symposium

Sean Smith, seansmith@ferrodevices.com – Symposium Organizer David Adams, dadams205@comcast.net – Short Course Organizer Tony Ohlhausen, TonyOhlhausen.nmavs@gmail.com - Vendor Show Organizer

The annual New Mexico AVS Technical Symposium will feature **SCIENTISTS AND ENGINEERS** at all levels of their career with special emphasis for **STUDENTS, TECHNOLOGISTS, AND EARLY CAREER RESEARCHERS**. This interdisciplinary, one-day forum allows for emerging scientists and engineers to present their research and collaborate with new colleagues. For students especially, the friendly exchange is valuable practice for future conferences and job presentations.

The <u>AVS – Science & Technology Society</u> is a non-profit professional society and a member of the <u>American Institute of Physics (AIP)</u>. <u>The New Mexico Chapter</u>, includes New Mexico, Arizona, Oklahoma and that part of Texas in the Mountain Time Zone. The AVS is the foremost professional organization for practitioners in the diverse fields that depend on science at low pressures and/or controlled atmospheres including films and coatings, microelectronics, nanostructures, surfaces and interfaces, plasmas, vacuum, and manufacturing processes.